MA2SP050G

Silicon epitaxial planar type

For high frequency attenuator

■ Features

- High performance forward current I_F controlled forward dynamic resistance r_f
- Small terminal capacitance C_t
- Miniature package and surface mounting type

■ Package

- Code
  SSMini2-F4
- Pin Name
  1: Anode
  2: Cathode

■ Marking Symbol: 6P

■ Absolute Maximum Ratings $T_a = 25°C$

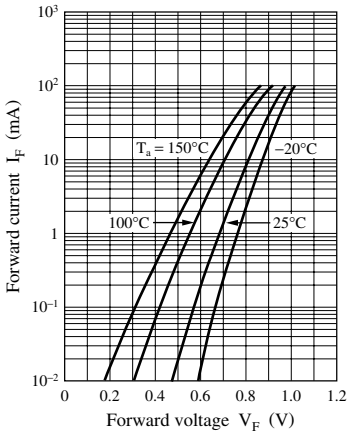
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	50	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

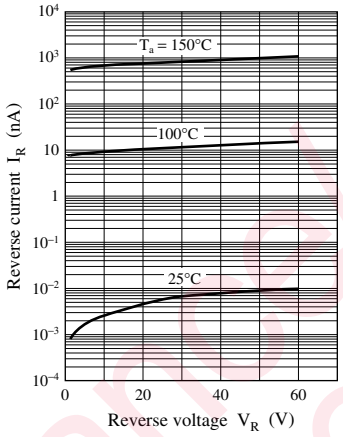
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA			1.0	V
Reverse current	I_R	$V_R = 60$ V			100	nA
Terminal capacitance	C_t	$V_R = 0$ V, f = 1 MHz			2.4	pF
Forward dynamic resistance	r_f	$I_F = 10$ mA, f = 100 MHz			5.5	Ω

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

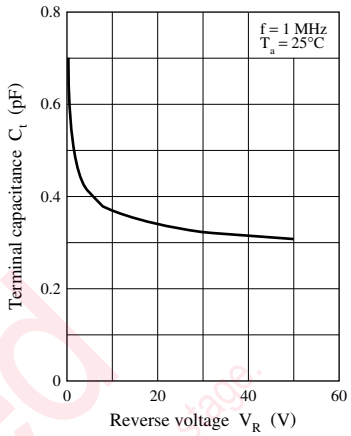
I_F — V_F



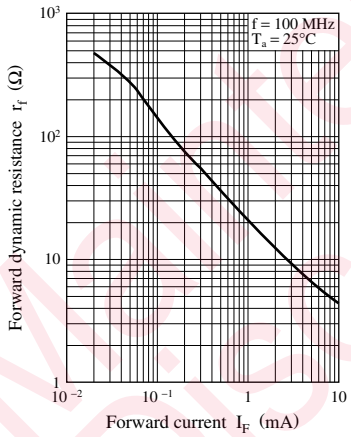
I_R — V_R



C_t — V_R

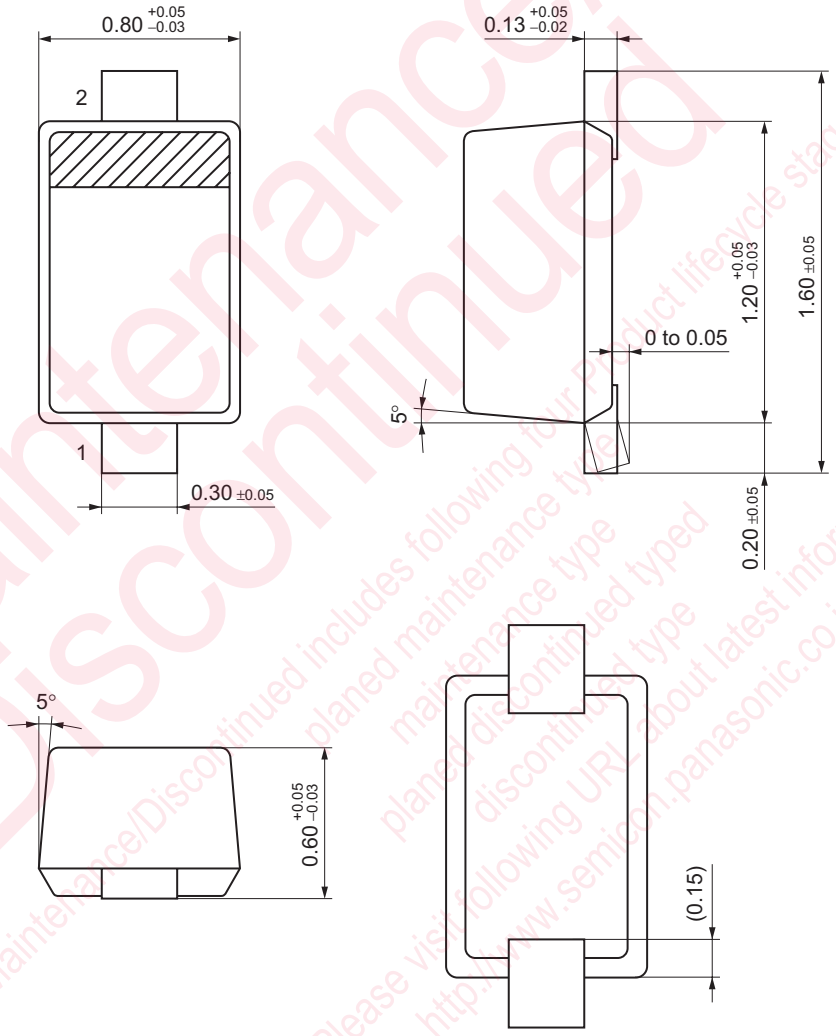


r_f — I_F



SSMini2-F4

Unit: mm



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